

CLIPPEDIMAGE= JP402275376A
PAT-NO: JP402275376A
DOCUMENT-IDENTIFIER: JP 02275376 A
TITLE: BURN IN METHOD

PUBN-DATE: November 9, 1990

INVENTOR-INFORMATION:
NAME
SAKUMA, KUNIO

ASSIGNEE-INFORMATION:
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COUNTRY
N/A

APPL-NO: JP01097775
APPL-DATE: April 18, 1989

INT-CL (IPC): G01R031/26; H01L021/66
US-CL-CURRENT: 324/765

ABSTRACT:

PURPOSE: To enable the implementing of a burn in being continued in a tape by winding a cylindrical support with a circuit board having IC sockets arranged spirally to set a semiconductor integrated circuit element carried on a film carrier.

CONSTITUTION: A cylindrical support 7 is wound with a substrate 8 having IC sockets 5 arranged spirally. In a burn in, a film carrier tape 1 is wound on the support 7 to match the socket 5 and a drive signal is inputted into an IC chip through the socket 5. Thus, a burn in processing is accomplished in a continuous tape without cutting the tape 1 in a short strip, thereby achieving a reduction in cost with a curtailment of a short-strip tape splicing process in a post process.

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DERWENT-ACC-NO: 1997-287116
DERWENT-WEEK: 199726
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TITLE: Rolled-type semiconductor chip e.g. thermoelectric transducer for e.g. thin film electrothermal conversion module - has main body which includes alternate layers of flexible film-like insulating substrate and semiconductor, rolled to form cylindrical shape

PATENT-ASSIGNEE: SHARP KK[SHAF]

PRIORITY-DATA: 1995JP-0261651 (October 9, 1995)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES	MAIN-IPC	
JP 09107129 A	April 22, 1997	N/A
008	H01L 035/32	

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP09107129A	N/A	1995JP-0261651
October 9, 1995		

INT-CL_(IPC): H01L035/32

ABSTRACTED-PUB-NO: JP09107129A

BASIC-ABSTRACT: The semiconductor chip (1) has a main body which includes several layers of flexible film-like insulating substrates (2) which are made of polyimide and teflon. A semiconductor (3), used for thermoelectric conversion, is formed on one side of each insulating substrate.

The main body is rolled to form a cylindrical shape. The semiconductor is a P-type heat conversion semiconductor with a super-lattice structure or an N-type heat conversion semiconductor.

ADVANTAGE - Enables easy formation of layered structure by rolling main body which includes alternate layers of insulating substrate and semiconductor. Enables easy setting of optimum shape of semiconductor chip due to use of film-like insulating substrate. Improves heat conversion function due to use of ultra thin semiconductor with super-lattice structure. Enables easy and efficient manufacturing of semiconductor chip with predetermined shape.

CHOSEN-DRAWING: Dwg.2/10

TITLE-TERMS:

ROLL TYPE SEMICONDUCTOR CHIP THERMOELECTRIC TRANSDUCER THIN
FILM ELECTROTHERMAL
CONVERT MODULE MAIN BODY ALTERNATE LAYER FLEXIBLE FILM
INSULATE SUBSTRATE
SEMICONDUCTOR ROLL FORM CYLINDER SHAPE

DERWENT-CLASS: U14

EPI-CODES: U14-E05A1;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1997-237830

L Number	Hits	Search Text	DB	Time stamp
-	136086	(cable or coaxial or cylinder or cylindrical) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:09
-	5649	((cable or coaxial or cylinder or cylindrical) same substrate) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 13:55
-	1734	((cable or coaxial or cylinder or cylindrical) same substrate) same (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 13:58
-	1499	((cable or coaxial or cylinder or cylindrical) same substrate) same (chip or die)) and (@ad<20000605)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:09
-	39245	(cable or coaxial or cylinder or cylindrical) with (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:10
-	5015	(cable or coaxial or cylinder or cylindrical or curve) near (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:51
-	235	((cable or coaxial or cylinder or cylindrical or curve) near (chip or die)) and (semiconductor or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:12
-	269	((cable or coaxial or cylinder or cylindrical or curve) near (chip or die)) and (semiconductor or ic or (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:13
-	114	((cable or coaxial or cylinder or cylindrical or curve) near (chip or die)) and ((semiconductor or ic or (integrated adj circuit)) adj (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:21
-	1	("5347086").PN.	USPAT	2002/05/31 14:21
-	8	5347086.URPN.	USPAT	2002/05/31 14:22
-	1	5203721.URPN.	USPAT	2002/05/31 14:39
-	132	((cable or coaxial or cylinder or cylindrical or curve) near (chip or die)) and (semiconductor or ic) not ((cable or coaxial or cylinder or cylindrical or curve) near (chip or die)) and ((semiconductor or ic or (integrated adj circuit)) adj (chip or die)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/31 14:59
-	8	semiconductor with polyhedral	US-PGPUB; IBM_TDB	2002/05/31 15:00

L Number	Hits	Search Text	DB	Time stamp
321	262	((cable or coaxial or cylinder or cylindrical) with (tape or flexible)) and (semiconductor near (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:13
322	0	((cable or coaxial or cylinder or cylindrical) with (tape or flexible)) and (semiconductor near (chip or die))) and (@ad20000605)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:14
323	228	((cable or coaxial or cylinder or cylindrical) with (tape or flexible)) and (semiconductor near (chip or die))) and (@ad<20000605)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:32
324	72	4833568.URPN.	USPAT	2002/05/31 18:24
325	422	438/455.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37
326	1759	438/106.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37
327	440	438/108.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37
328	1185	257/778.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37
329	415	257/782.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37
330	1303	257/678.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37
331	263	257/731.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/31 18:37